

74LVC1G14

Single Schmitt-trigger inverter

Rev. 12 — 6 August 2012

Product data sheet

1. General description

The 74LVC1G14 provides the inverting buffer function with Schmitt-trigger input. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

The input can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device in a mixed 3.3 V and 5 V environment. Schmitt-trigger action at the input makes the circuit tolerant for slower input rise and fall time.

This device is fully specified for partial power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 1.65 V to 5.5 V
- High noise immunity
- Complies with JEDEC standard:
 - ◆ JESD8-7 (1.65 V to 1.95 V)
 - ◆ JESD8-5 (2.3 V to 2.7 V)
 - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V).
- ± 24 mA output drive ($V_{CC} = 3.0$ V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Unlimited rise and fall times
- Input accepts voltages up to 5 V
- Multiple package options
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V.
- Specified from -40 °C to $+85$ °C and -40 °C to $+125$ °C.

3. Applications

- Wave and pulse shaper
- Astable multivibrator
- Monostable multivibrator



4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC1G14GW	−40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74LVC1G14GV	−40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74LVC1G14GM	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74LVC1G14GF	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74LVC1G14GN	−40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74LVC1G14GS	−40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74LVC1G14GX	−40 °C to +125 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226

5. Marking

Table 2. Marking

Type number	Marking code ^[1]
74LVC1G14GW	VF
74LVC1G14GV	V14
74LVC1G14GM	VF
74LVC1G14GF	VF
74LVC1G14GN	VF
74LVC1G14GS	VF
74LVC1G14GX	VF

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

6. Functional diagram

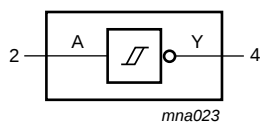


Fig 1. Logic symbol

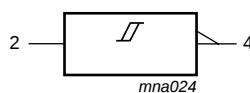


Fig 2. IEC logic symbol

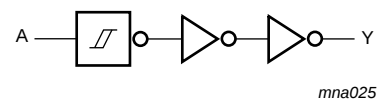
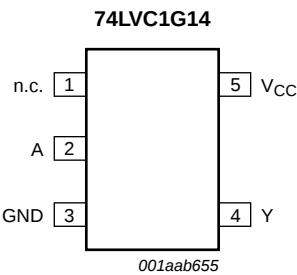


Fig 3. Logic diagram

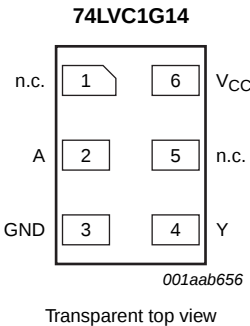
7. Pinning information

7.1 Pinning



74LVC1G14

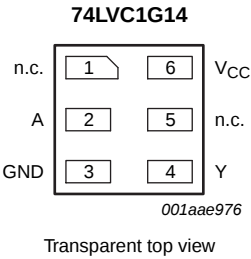
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74LVC1G14

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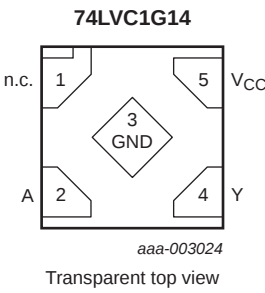
Transparent top view



74LVC1G14

001aae976

Transparent top view



74LVC1G14

aaa-003024

Transparent top view

Fig 4. Pin configuration SOT353-1 and SOT753

Fig 5. Pin configuration SOT886

Fig 6. Pin configuration SOT891, SOT1115 and SOT1202

Fig 7. Pin configuration SOT1226 (X2SON5)

7.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	TSSOP5 and X2SON5	XSON6	
n.c.	1	1	not connected
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V _{CC}	5	6	supply voltage

8. Functional description

Table 4. Function table^[1]

Input	Output
A	Y
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level

9. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
V_I	input voltage		^[1] -0.5	+6.5	V
V_O	output voltage	Active mode	^{[1][2]} -0.5	$V_{CC} + 0.5$	V
		Power-down mode	^{[1][2]} -0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
I_O	output current	$V_O = 0$ V to V_{CC}	-	±50	mA
I_{CC}	supply current		-	+100	mA
I_{GND}	ground current		-100	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	^[3] -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When $V_{CC} = 0$ V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For TSSOP5 and SC-74A packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.
For XSON6 and X2SON5 package: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

10. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	5.5	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage	Active mode	0	-	V_{CC}	V
		Power-down mode; $V_{CC} = 0$ V	0	-	5.5	V
T_{amb}	ambient temperature		-40	-	+125	°C

11. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{OH}	HIGH-level output voltage	V _I = V _{T+} or V _{T–}						
		I _O = –100 µA; V _{CC} = 1.65 V to 5.5 V	V _{CC} – 0.1	-	-	V _{CC} – 0.1	-	V
		I _O = –4 mA; V _{CC} = 1.65 V	1.2	1.54	-	0.95	-	V
		I _O = –8 mA; V _{CC} = 2.3 V	1.9	2.15	-	1.7	-	V
		I _O = –12 mA; V _{CC} = 2.7 V	2.2	2.50	-	1.9	-	V
		I _O = –24 mA; V _{CC} = 3.0 V	2.3	2.62	-	2.0	-	V
V _{OL}	LOW-level output voltage	V _I = V _{T+} or V _{T–}						
		I _O = 100 µA; V _{CC} = 1.65 V to 5.5 V	-	-	0.10	-	0.10	V
		I _O = 4 mA; V _{CC} = 1.65 V	-	0.07	0.45	-	0.70	V
		I _O = 8 mA; V _{CC} = 2.3 V	-	0.12	0.30	-	0.45	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	0.17	0.40	-	0.60	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	0.33	0.55	-	0.80	V
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	±0.1	±5	-	±100	µA
		V _I or V _O = 5.5 V; V _{CC} = 0 V	-	±0.1	±10	-	±200	µA
I _{CC}	supply current	V _I = 5.5 V or GND; I _O = 0 A; V _{CC} = 1.65 V to 5.5 V	-	0.1	10	-	200	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} – 0.6 V; I _O = 0 A; V _{CC} = 2.3 V to 5.5 V	-	5	500	-	5000	µA
C _I	input capacitance	V _{CC} = 3.3 V; V _I = GND to V _{CC}	-	5.0	-	-	-	pF

[1] All typical values are measured at maximum V_{CC} and T_{amb} = 25 °C.

Table 8. Transfer characteristics

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 9](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{T+}	positive-going threshold voltage	see Figure 10 and Figure 11						
		V _{CC} = 1.8 V	0.82	1.0	1.14	0.79	1.14	V
		V _{CC} = 2.3 V	1.03	1.2	1.40	1.00	1.40	V
		V _{CC} = 3.0 V	1.29	1.5	1.71	1.26	1.71	V
		V _{CC} = 4.5 V	1.84	2.1	2.36	1.81	2.36	V
		V _{CC} = 5.5 V	2.19	2.5	2.79	2.16	2.79	V

Table 8. Transfer characteristics ...continued

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 9](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{T–}	negative-going threshold voltage	see Figure 10 and Figure 11						
		V _{CC} = 1.8 V	0.46	0.6	0.75	0.46	0.78	V
		V _{CC} = 2.3 V	0.65	0.8	0.96	0.65	0.99	V
		V _{CC} = 3.0 V	0.88	1.0	1.24	0.88	1.27	V
		V _{CC} = 4.5 V	1.32	1.5	1.84	1.32	1.87	V
		V _{CC} = 5.5 V	1.58	1.8	2.24	1.58	2.27	V
V _H	hysteresis voltage	(V _{T+} – V _{T–}); see Figure 10 , Figure 11 and Figure 12						
		V _{CC} = 1.8 V	0.26	0.4	0.51	0.19	0.51	V
		V _{CC} = 2.3 V	0.28	0.4	0.57	0.22	0.57	V
		V _{CC} = 3.0 V	0.31	0.5	0.64	0.25	0.64	V
		V _{CC} = 4.5 V	0.40	0.6	0.77	0.34	0.77	V
		V _{CC} = 5.5 V	0.47	0.6	0.88	0.41	0.88	V

[1] All typical values are measured at T_{amb} = 25 °C

12. Dynamic characteristics

Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for load circuit see [Figure 9](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	A to Y; see Figure 8 ^[2]						
		V _{CC} = 1.65 V to 1.95 V	1.0	4.1	11.0	1.0	14.0	ns
		V _{CC} = 2.3 V to 2.7 V	0.7	2.8	6.5	0.7	8.5	ns
		V _{CC} = 2.7 V	0.7	3.2	6.5	0.7	8.5	ns
		V _{CC} = 3.0 V to 3.6 V	0.7	3.0	5.5	0.7	7.0	ns
		V _{CC} = 4.5 V to 5.5 V	0.7	2.2	5.0	0.7	6.5	ns
C _{PD}	power dissipation capacitance	V _{CC} = 3.3 V; V _I = GND to V _{CC} ^[3]	-	15.4	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.8 V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i + (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in V.

13. Waveforms

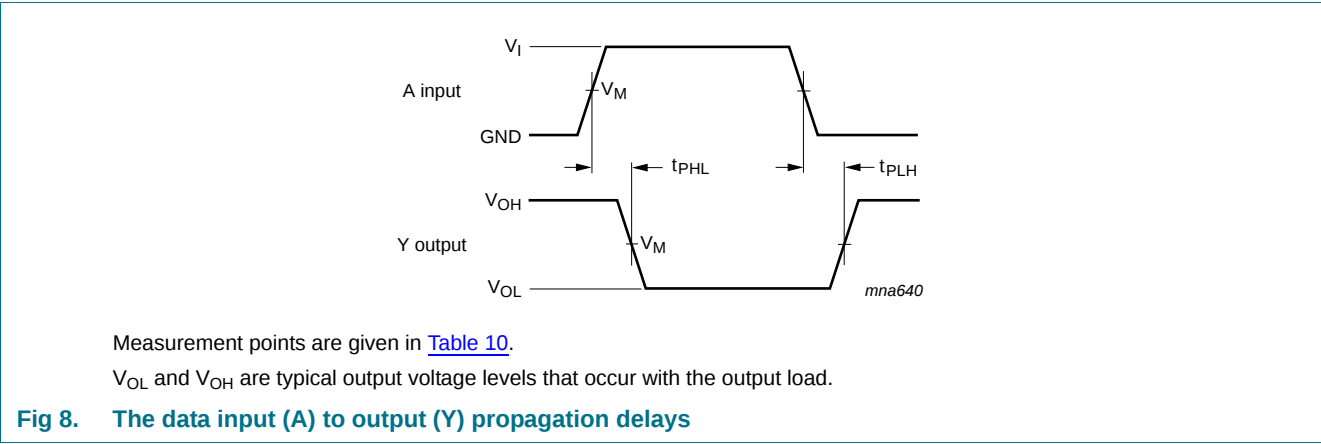


Table 10. Measurement points

Supply voltage	Input	Output
V_{CC}	V_M	V_M
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V
4.5 V to 5.5 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

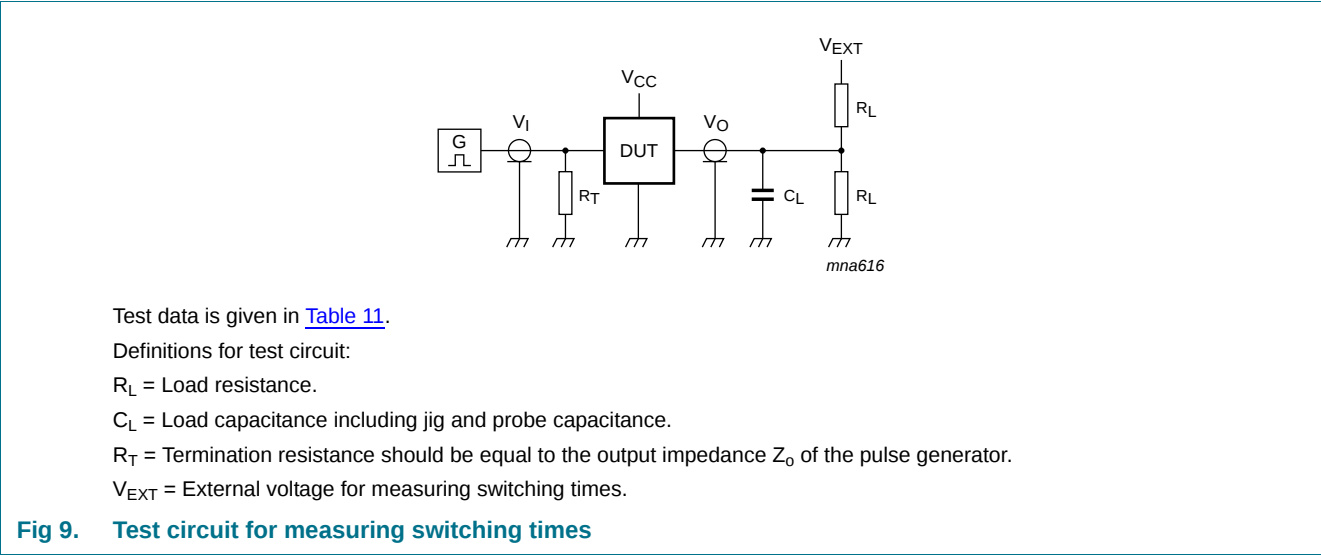
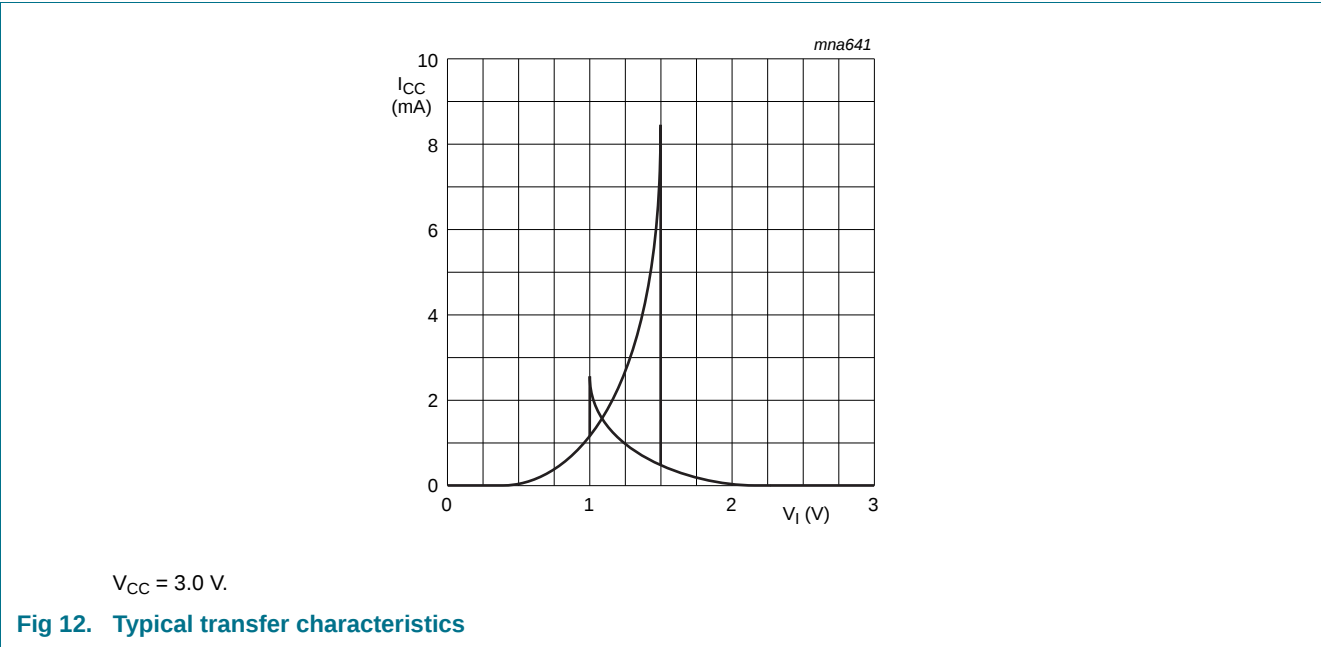
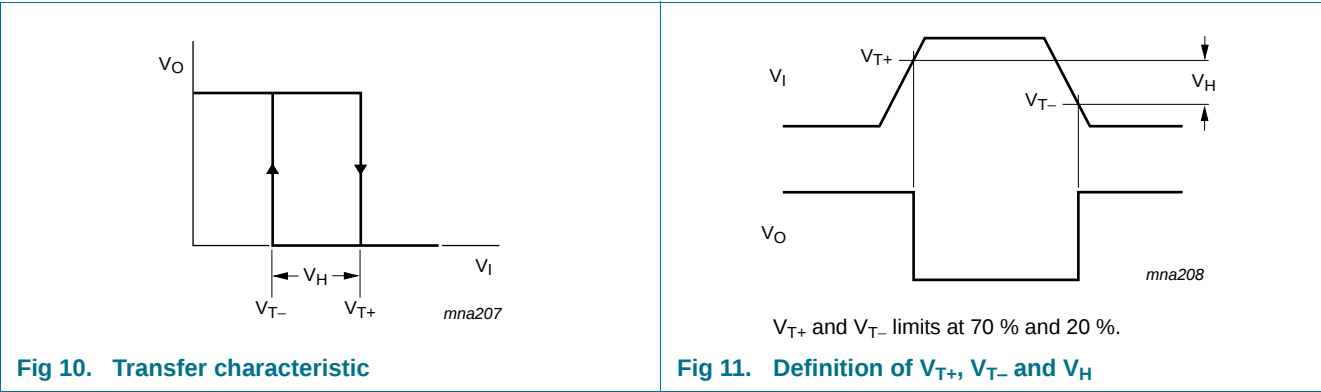


Table 11. Test data

Supply voltage	Input		Load		V _{EXT}
V _{CC}	V _I	t _r = t _f	C _L	R _L	t _{PLH} , t _{PHL}
1.65 V to 1.95 V	V _{CC}	≤ 2.0 ns	30 pF	1 kΩ	open
2.3 V to 2.7 V	V _{CC}	≤ 2.0 ns	30 pF	500 Ω	open
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
4.5 V to 5.5 V	V _{CC}	≤ 2.5 ns	50 pF	500 Ω	open

14. Waveforms transfer characteristics



15. Application information

The slow input rise and fall times cause additional power dissipation, this can be calculated using the following formula:

$$P_{\text{add}} = f_i \times (t_r \times \Delta I_{\text{CC(AV)}} + t_f \times \Delta I_{\text{CC(AV)}}) \times V_{\text{CC}} \text{ where:}$$

P_{add} = additional power dissipation (μW);

f_i = input frequency (MHz);

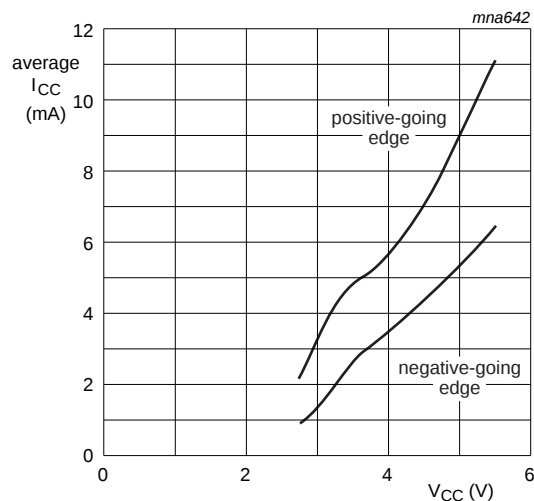
t_r = input rise time (ns); 10 % to 90 %;

t_f = input fall time (ns); 90 % to 10 %;

$\Delta I_{\text{CC(AV)}}$ = average additional supply current (μA).

Average $\Delta I_{\text{CC(AV)}}$ differs with positive or negative input transitions, as shown in [Figure 13](#).

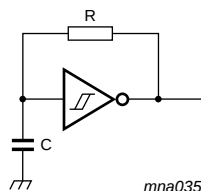
An example of a relaxation circuit using the 74LVC1G14 is shown in [Figure 14](#).



Linear change of V_I between 0.8 V to 2.0 V.

All values given are typical unless otherwise specified.

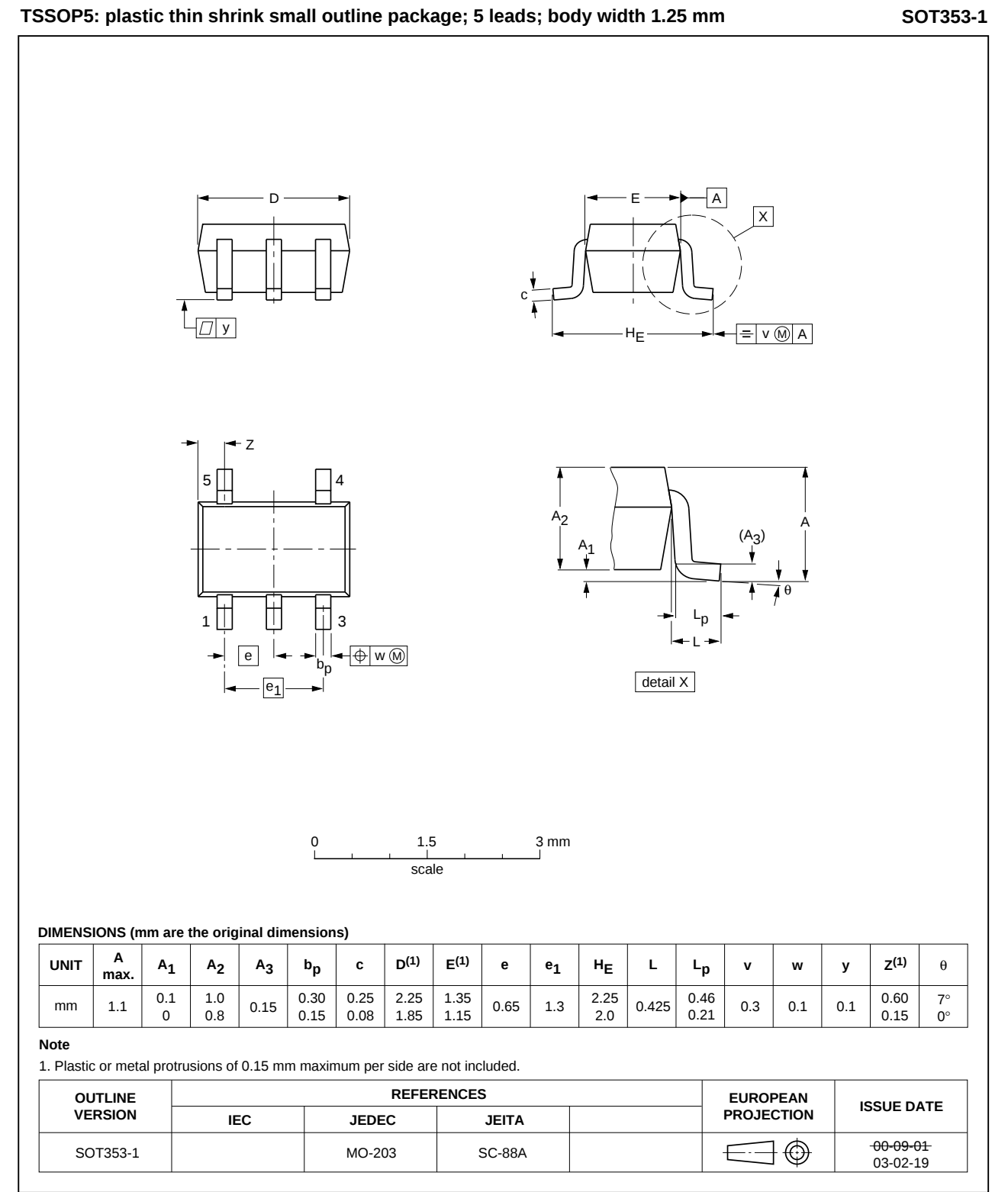
Fig 13. Average additional supply current as a function of supply voltage



$$f = \frac{1}{T} \approx \frac{1}{0.5 \times RC}$$

Fig 14. Relaxation oscillator

16. Package outline



Plastic surface-mounted package; 5 leads

SOT753

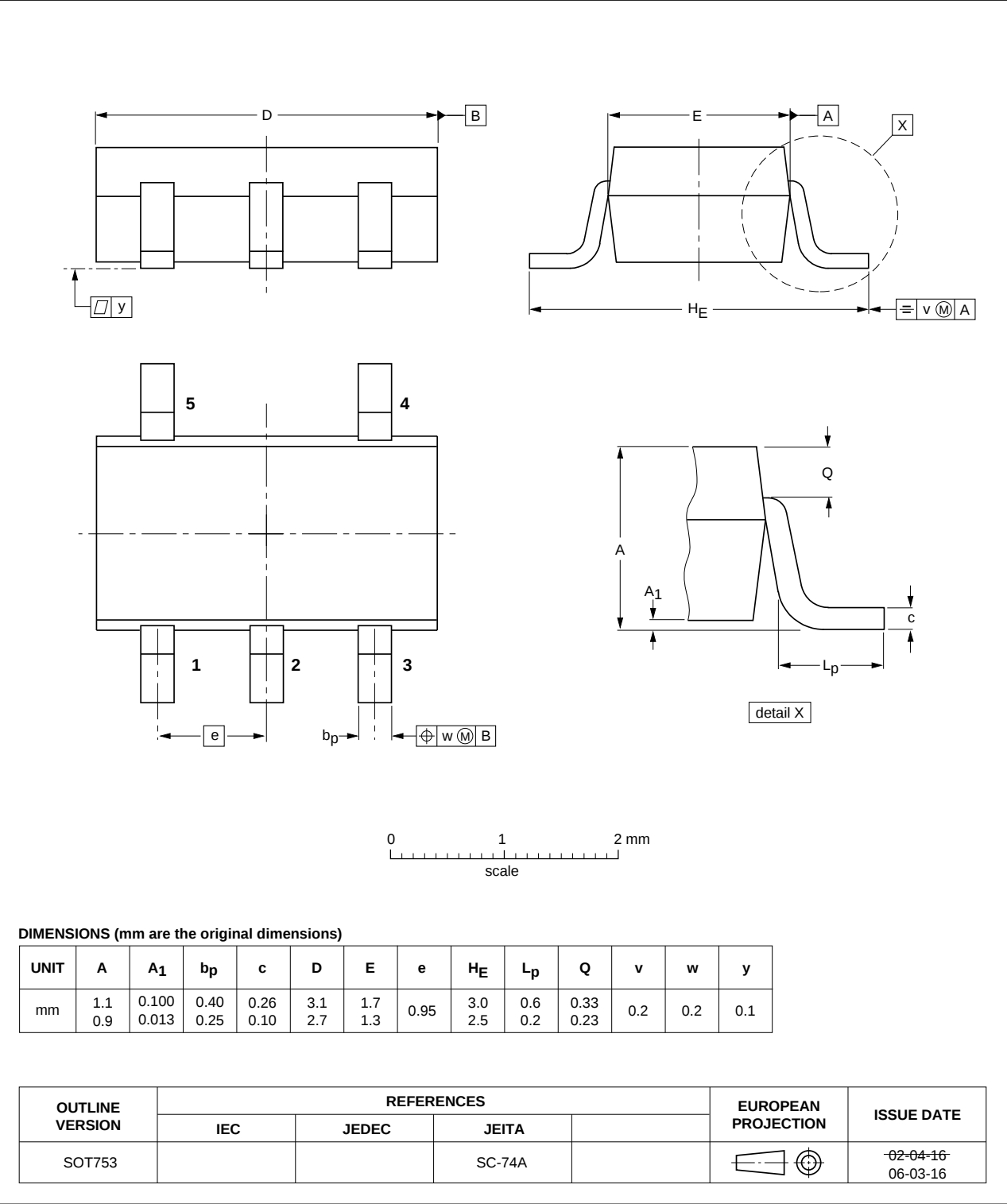


Fig 16. Package outline SOT753 (SC-74A)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

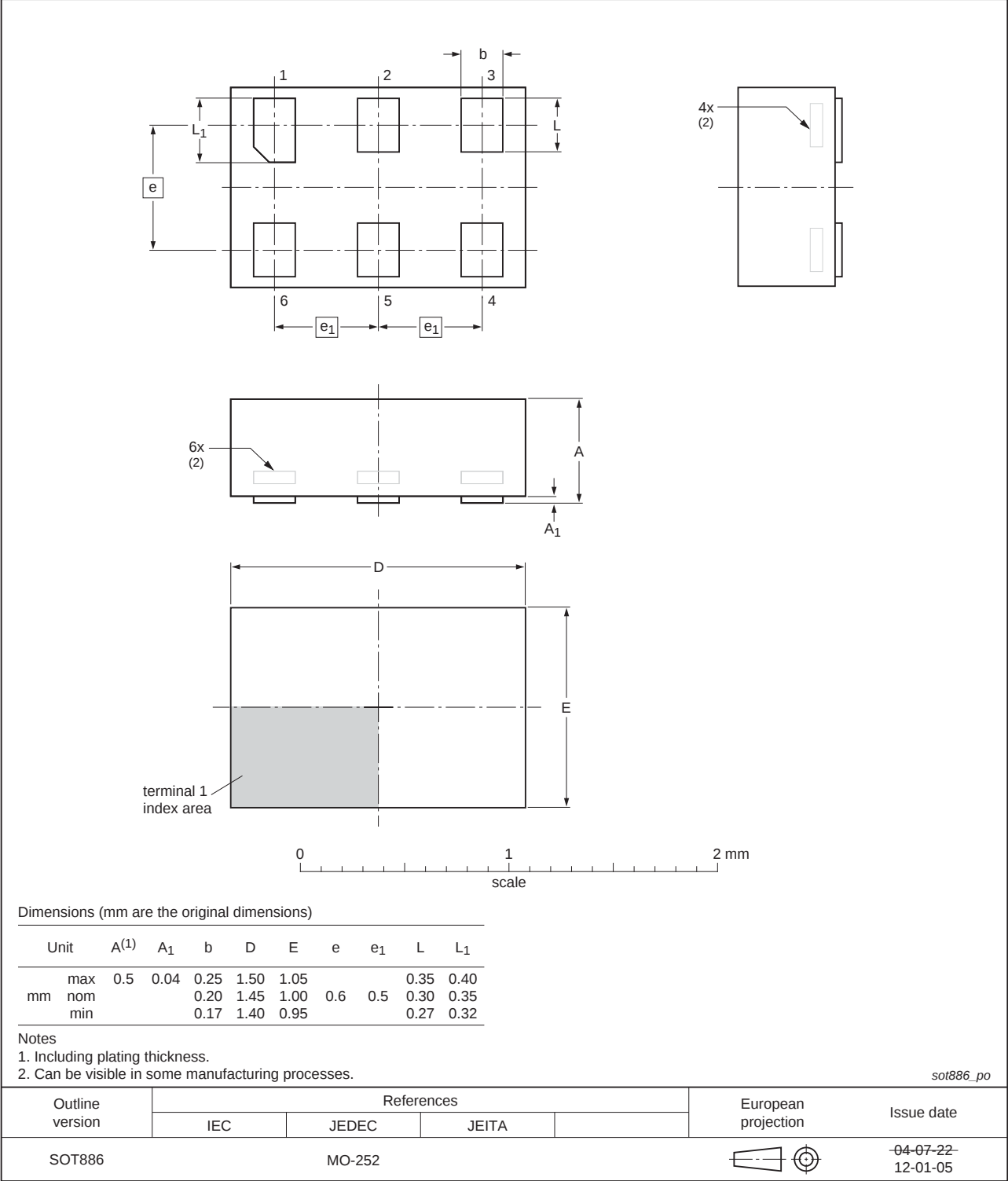


Fig 17. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

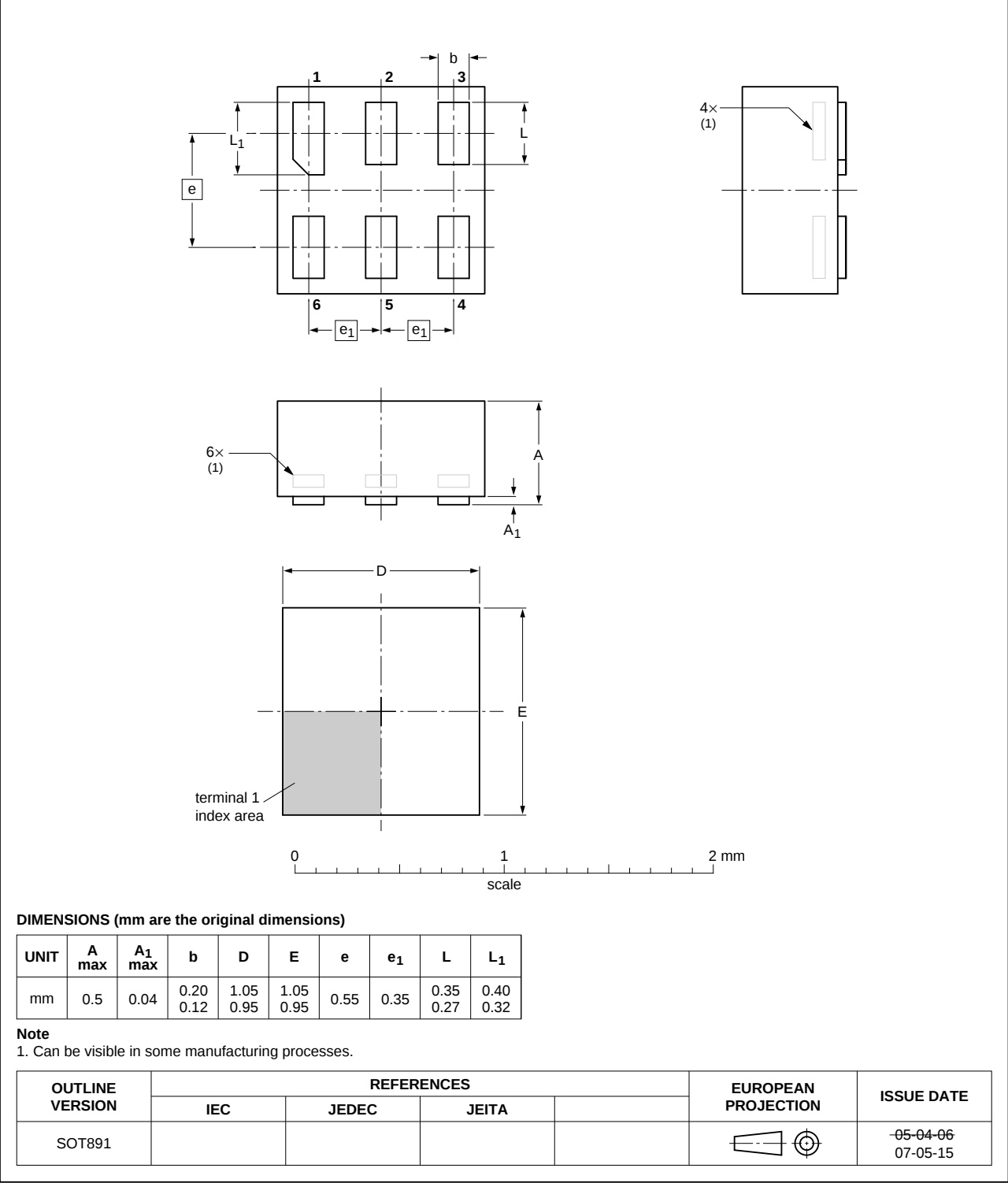


Fig 18. Package outline SOT891 (XSON6)

XSON6: extremely thin small outline package; no leads;
6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
mm	max	0.35	0.04	0.20	0.95	1.05		0.35	0.40
	nom			0.15	0.90	1.00	0.55	0.30	0.35
	min			0.12	0.85	0.95		0.27	0.32

Note

- 1. Including plating thickness.
- 2. Visible depending upon used manufacturing technology.

sot1115_po

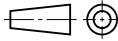
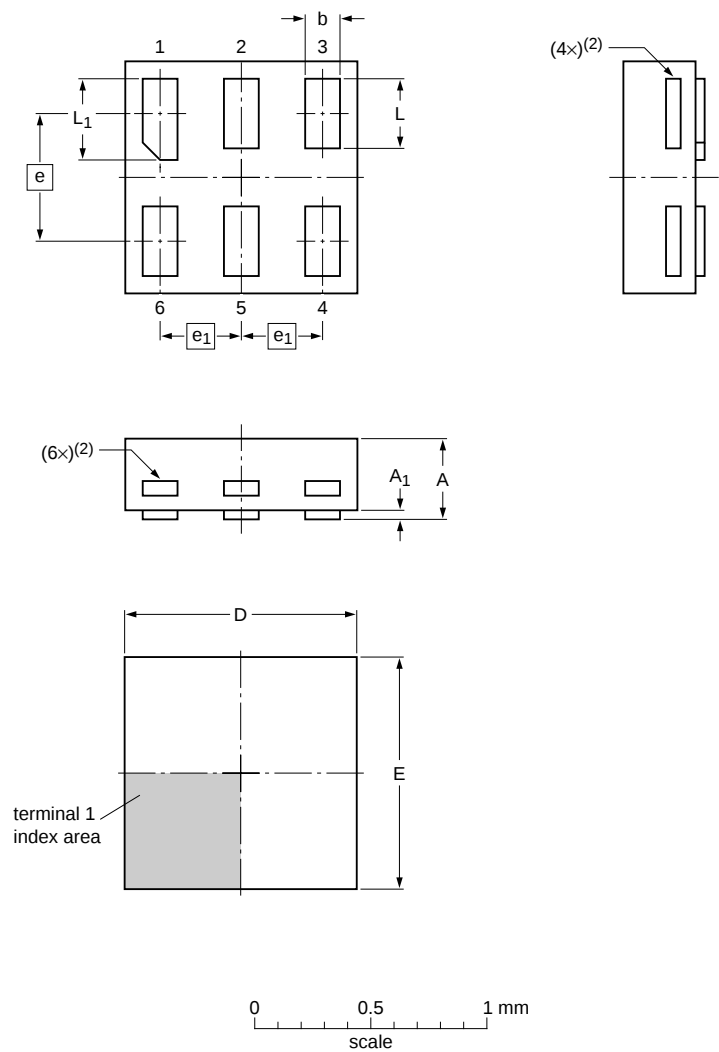
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1115						10-04-02 10-04-07

Fig 19. Package outline SOT1115 (XSON6)

XSON6: extremely thin small outline package; no leads;
6 terminals; body 1.0 x 1.0 x 0.35 mm

SOT1202



Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
mm	max	0.35	0.04	0.20	1.05	1.05		0.35	0.40
	nom			0.15	1.00	1.00	0.55	0.30	0.35
	min			0.12	0.95	0.95		0.27	0.32

Note

- 1. Including plating thickness.
- 2. Visible depending upon used manufacturing technology.

sot1202_po

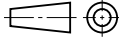
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1202						10-04-02 10-04-06

Fig 20. Package outline SOT1202 (XSON6)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

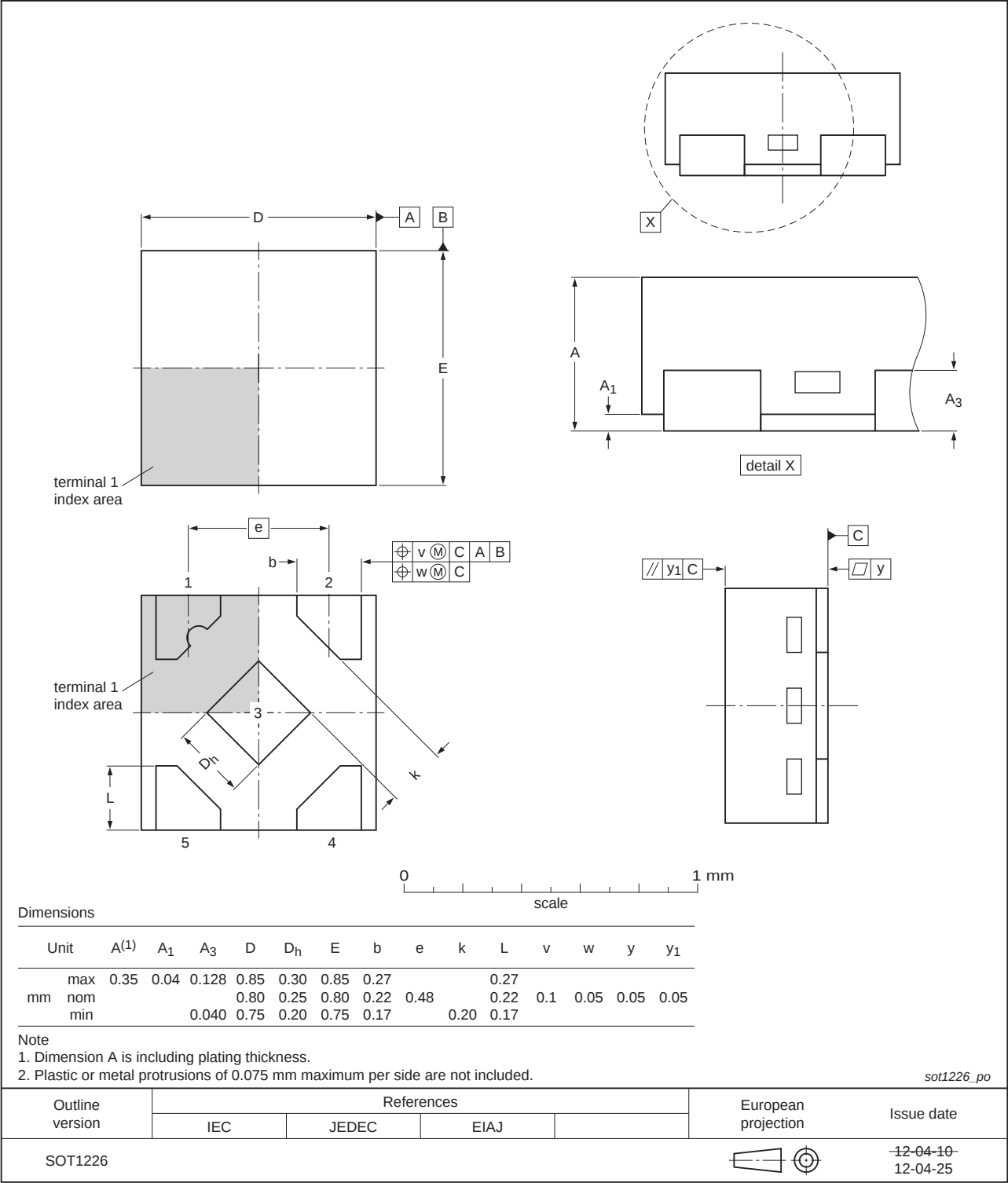


Fig 21. Package outline SOT1226 (X2SON5)

17. Abbreviations

Table 12. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
TTL	Transistor-Transistor Logic
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
DUT	Device Under Test

18. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC1G14 v.12	20120806	Product data sheet	-	74LVC1G14 v.11
Modifications:	Package outline drawing of SOT1226 (Figure 21) modified.			
74LVC1G14 v.11	20120412	Product data sheet	-	74LVC1G14 v.10
Modifications:	- Added type number 74LVC1G14GX (SOT1226) - Package outline drawing of SOT886 (Figure 17) modified.			
74LVC1G14 v.10	20111206	Product data sheet	-	74LVC1G14 v.9
Modifications:	Legal pages updated.			
74LVC1G14 v.9	20110922	Product data sheet	-	74LVC1G14 v.8
74LVC1G14 v.8	20101110	Product data sheet	-	74LVC1G14 v.7
74LVC1G14 v.7	20070718	Product data sheet	-	74LVC1G14 v.6
74LVC1G14 v.6	20060615	Product data sheet	-	74LVC1G14 v.5
74LVC1G14 v.5	20040910	Product specification	-	74LVC1G14 v.4
74LVC1G14 v.4	20021119	Product specification	-	74LVC1G14 v.3
74LVC1G14 v.3	20020521	Product specification	-	74LVC1G14 v.2
74LVC1G14 v.2	20010406	Product specification	-	74LVC1G14 v.1
74LVC1G14 v.1	20001212	Product specification	-	-

19. Legal information

19.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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